



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STU7N65M2	TSIK*MQF0B6F	A	Z8GA	2016-04-28
Amount		UoM	Unit type	ST ECOPACK Grade
310.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	6.1 - 6.5 - 2.3	3	Through-hole	
Comment	Package: IPAK TO-251			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TSIK*MQF086F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.485	mg	supplier	die	Silicon (Si)	7440-21-3		3.346	mg	960115	10794
				supplier	metallization	Aluminium (Al)	7429-90-5		0.066	mg	18938	213
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	4590	52
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	6887	77
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	574	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.023	mg	6600	74
Lead-frame	Copper & its alloys	148.756	mg	Supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	2296	26
				Supplier	Alloy	Copper (Cu)	7440-50-8		148.446	mg	997916	478858
				Supplier	Alloy	Iron (Fe)	7439-89-6		0.149	mg	1002	481
				Supplier	Alloy	Phosphorus (P)	12185-10-3		0.046	mg	309	148
				Supplier	Alloy	Nickel (Ni)	7440-02-0		0.115	mg	773	371
Soft solder	Solder	1.473	mg	supplier	solder	Tin(Sn)	7440-31-5		0.003	mg	2037	10
				supplier	solder	Silver (Ag)	7440-22-4		0.038	mg	25798	123
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.432	mg	972166	4617
Bonding wire	Other inorganic materials	0.964	mg	supplier	Bonding wire	Aluminum(Al)	84195-93-7		0.964	mg	1000000	3110
Encapsulation	Other Organic Materials	150.066	mg	supplier	Molding compound	Silica Fused	60676-86-0		120.053	mg	800001	387268
				supplier	Molding compound	Epoxy Resin	25068-38-6		15.008	mg	100009	48413
				supplier	Molding compound	Phenol Resin	29690-82-2		9.754	mg	64998	31465
				supplier	Molding compound	Carbon Black	14808-60-7		5.251	mg	34991	16939
Connections coating	Solder	5.256	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		5.256	mg	1000000	16955